

MOSFET - N-Channel, DUAL COOL[®] 88, POWERTRENCH[®]

100 V, 162 A, 2.95 mΩ

FDMT800100DC

概述

此 N 沟道 MOSFET 采用 onsemi 先进的 POWERTRENCH 工艺生产。先进的硅技术和 DUAL COOL 封装技术完美融合, 可在提供最小 $r_{DS(on)}$ 的同时通过极低的结至环境热阻保持卓越的开关性能。

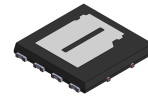
特性

- 最大值 $r_{DS(on)} = 2.95 \text{ m}\Omega$ ($V_{GS} = 10 \text{ V}$ 、 $I_D = 24 \text{ A}$)
- 最大值 $r_{DS(on)} = 4.46 \text{ m}\Omega$ ($V_{GS} = 6 \text{ V}$ 、 $I_D = 19 \text{ A}$)
- 低 $r_{DS(on)}$ 和高效的先进硅封装
- 下一代先进体二极管技术, 专为软恢复设计
- 薄型 8 x 8 mm MLP 封装
- MSL1 强健封装设计
- 100% 经过 UIL 测试
- 此器件不含铅, 无卤, 符合 RoHS 标准

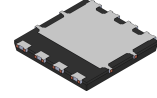
应用

- OringFET / 负载开关
- 同步整流
- DC-DC 转换

V_{DS}	$r_{DS(on)}$ MAX	I_D MAX
100 V	2.95 mΩ @ 10 V	162 A
	4.46 mΩ @ 6 V	



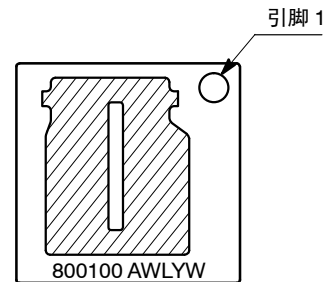
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底

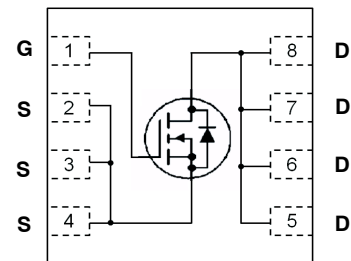
TDFNW8 8.3 x 8.4, 2P,
DUAL COOL, OPTION 2
CASE 507AR

MARKING DIAGRAM



800100 = Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
W = Work Week

ELECTRICAL CONNECTION



N-Channel MOSFET

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 7 of this data sheet.

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MOSFET 最大额定值 ($T_A = 25^\circ\text{C}$, 除非另有说明)

符号	参数		单位
V_{DS}	漏极 — 源极电压		V
V_{GS}	栅极 — 源极电压+		V
I_D	漏极电流 - 连续 $T_C = 25^\circ\text{C}$ (注 5)	162	A
	- 脉冲 $T_C = 100^\circ\text{C}$ (注 5)	102	
	- 连续 $T_A = 25^\circ\text{C}$ (注 1a)	24	
	- 雪崩电流 (注 4)	989	
E_{AS}	单脉冲雪崩能量 (注 3)	1536	mJ
P_D	功耗 $T_C = 25^\circ\text{C}$	156	W
	功耗 $T_A = 25^\circ\text{C}$ (注 1a)	3.2	
T_J, T_{STG}	工作和保存结温范围	-55 至 +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

(参考译文)

如果电压超过最大额定值表中列出的值范围，器件可能会损坏。如果超过任何这些限值，将无法保证器件功能，可能会导致器件损坏，影响可靠性。

热特性

符号	参数		单位
$R_{\theta JC}$	结至外壳热阻 (顶部源极)	1.6	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	结至外壳热阻 (底部源极)	0.8	
$R_{\theta JA}$	结至环境热阻 (注 1a)	38	
$R_{\theta JA}$	结至环境热阻 (注 1b)	81	
$R_{\theta JA}$	结至环境热阻 (注 1i)	15	
$R_{\theta JA}$	结至环境热阻 (注 1j)	21	
$R_{\theta JA}$	结至环境热阻 (注 1k)	9	

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电气特性 (T_J = 25°C, 除非另有说明)

符号	参数	测试条件	最小值	典型值	最大值	单位
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关断特性

BV _{DSS}	漏极-源极击穿电压	I _D = 250 μA, V _{GS} = 0 V	100	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	击穿电压温度系数	I _D = 250 μA, 参考 25°C	-	66	-	mV/°C
I _{DSS}	零栅极电压漏极电流	V _{DS} = 80 V, V _{GS} = 0 V	-	-	1	μA
I _{GSS}	栅极-源极漏电流	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	100	nA

导通特性

V _{GS(th)}	栅极至源极阈值电压	V _{GS} = V _{DS} , I _D = 250 μA	2.0	2.8	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	栅极至源极阈值电压温度系数	I _D = 250 μA, 参考 25°C	-	-11	-	mV/°C
r _{DS(on)}	漏极至源极静态导通电阻	V _{GS} = 10 V, I _D = 24 A	-	2.3	2.95	mΩ
		V _{GS} = 6 V, I _D = 19 A	-	3.5	4.46	
		V _{GS} = 10 V, I _D = 24 A, T _J = 125°C	-	4.2	5.39	
g _{FS}	正向跨导	V _{DS} = 5 V, I _D = 24 A	-	66	-	S

动态特性

C _{iss}	输入电容	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	-	5595	7835	pF
C _{oss}	输出电容		-	1160	1625	pF
C _{rss}	反向传输电容		-	39	75	pF
R _g	栅极阻抗		0.1	1.4	3.5	Ω

开关特性

t _{d(on)}	导通延迟时间	V _{DD} = 50 V, I _D = 24 A, V _{GS} = 10 V, R _{GEN} = 6 Ω	-	29	47	ns
t _r	上升时间		-	18	33	
t _{d(off)}	关断延迟时间		-	40	64	
t _f	下降时间		-	10	20	
Q _{g(TOT)}	总栅极电荷	V _{GS} = 0 V 至 10 V, V _{DD} = 50 V, I _D = 24 A	-	79	111	nC
		V _{GS} = 0 V 至 6 V, V _{DD} = 50 V, I _D = 24 A	-	50	70	
Q _{gs}	栅极-源极电荷	V _{DD} = 50 V, I _D = 24 A	-	23	-	nC
Q _{gd}	栅极-漏极“米勒”电荷		-	16	-	nC

漏极-源极二极管特性

V _{SD}	源极-漏极二极管正向电压	V _{GS} = 0 V, I _S = 2.9 A (注 2)	-	0.7	1.1	V
		V _{GS} = 0 V, I _S = 24 A (注 2)	-	0.8	1.2	
t _{rr}	反向恢复时间	I _F = 24 A, di/dt = 100 A/μs	-	71	114	ns
Q _{rr}	反向恢复电荷		-	94	151	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

(参考译文)

除非另有说明,“电气特性”表格中列出的是所列测试条件下的产品性能参数。如果在不同条件下运行,产品性能可能与“电气特性”表格中所列性能参数不一致。

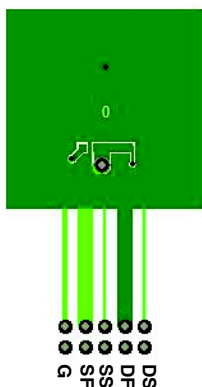
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热特性

符号	参数	单位
$R_{\theta JC}$	结至外壳热阻 (顶部源极)	1.6
$R_{\theta JC}$	结至外壳热阻 (底部源极)	0.8
$R_{\theta JA}$	结至环境热阻 (注 1a)	38
$R_{\theta JA}$	结至环境热阻 (注 1b)	81
$R_{\theta JA}$	结至环境热阻 (注 1c)	26
$R_{\theta JA}$	结至环境热阻 (注 1d)	34
$R_{\theta JA}$	结至环境热阻 (注 1e)	14
$R_{\theta JA}$	结至环境热阻 (注 1f)	16
$R_{\theta JA}$	结至环境热阻 (注 1g)	26
$R_{\theta JA}$	结至环境热阻 (注 1h)	60
$R_{\theta JA}$	结至环境热阻 (注 1i)	15
$R_{\theta JA}$	结至环境热阻 (注 1j)	21
$R_{\theta JA}$	结至环境热阻 (注 1k)	9
$R_{\theta JA}$	结至环境热阻 (注 1l)	11

注:

1. $R_{\theta JA}$ 通过安装在 FR-4 电路板上的器件确定, 该电路板使用指定的 2 oz 铜焊盘, 如下图所示。 $R_{\theta CA}$ 由用户的电路板设计确定。



a) 38°C/W (安装于 a 1 平方英寸 2 oz 铜焊盘)



b) 81°C/W (安装于最小 2 oz 铜焊盘)

- c) 静止空气, 20.9 × 10.4 × 12.7 mm 铝质散热器, 1 平方英寸 2 oz 铜焊盘
- d) 静止空气, 20.9 × 10.4 × 12.7 mm 铝质散热器, 最小 2 oz 铜焊盘
- e) 静止空气, 45.2 × 41.4 × 11.7 mm Aavid Thermalloy 器件号 10-L41B-11 散热器, 1 平方英寸 2 oz 铜焊盘
- f) 静止空气, 45.2 × 41.4 × 11.7 mm Aavid Thermalloy 器件号 10-L41B-11 散热器, 最小 2 oz 铜焊盘
- g) 200FPM 气流, 无散热器, 1 平方英寸 2 oz 铜焊盘
- h) 200FPM 气流, 无散热器, 最小 2 oz 铜焊盘
- i) 200FPM 气流, 20.9 × 10.4 × 12.7 mm 铝质散热器, 1 平方英寸 2 oz 铜焊盘
- j) 200FPM 气流, 20.9 × 10.4 × 12.7 mm 铝质散热器, 最小 2 oz 铜焊盘
- k) 200FPM 气流, 45.2 × 41.4 × 11.7 mm Aavid Thermalloy 器件号 10-L41B-11 散热器, 1 平方英寸 2 oz 铜焊盘
- l) 200FPM 气流, 45.2 × 41.4 × 11.7 mm Aavid Thermalloy 器件号 10-L41B-11 散热器, 最小 2 oz 铜焊盘

2. 脉冲测试: 脉冲宽度: < 300 ms, 占空比: < 2.0%。

3. E_{AS} 为 1536 mJ, 基于起始 $T_J = 25^\circ\text{C}$; N-ch: $L = 3 \text{ mH}$, $I_{AS} = 32 \text{ A}$, $V_{DD} = 100 \text{ V}$, $V_{GS} = 10 \text{ V}$ 。100% test at ($L = 0.1 \text{ mH}$, $I_{AS} = 101 \text{ A}$ 。)

4. 有关脉冲编号的更多详情, 请参考图 11 中的 SOA 图形。

5. 计算得到的连续电流仅限于最大结温, 实际连续电流将受限于散热以及电气机械应用的电路板设计。

典型特性 ($T_J = 25^\circ\text{C}$, 除非另有说明)

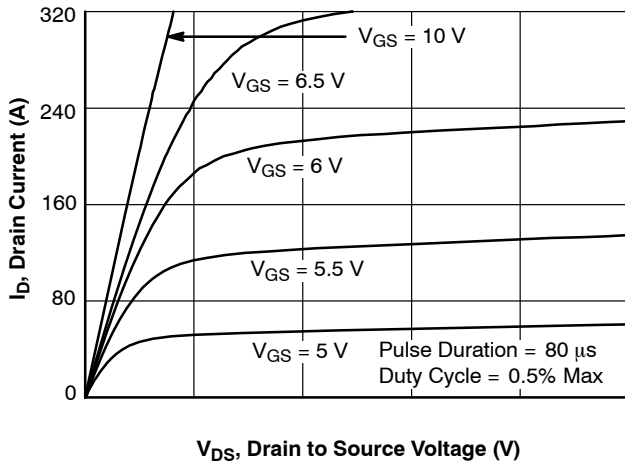


图 1. 通态区域特性

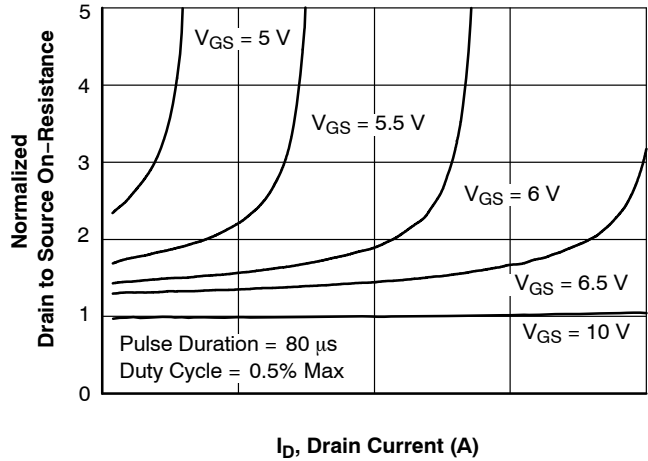


图 2. 标准化导通电阻与漏极电流和栅极电压的关系

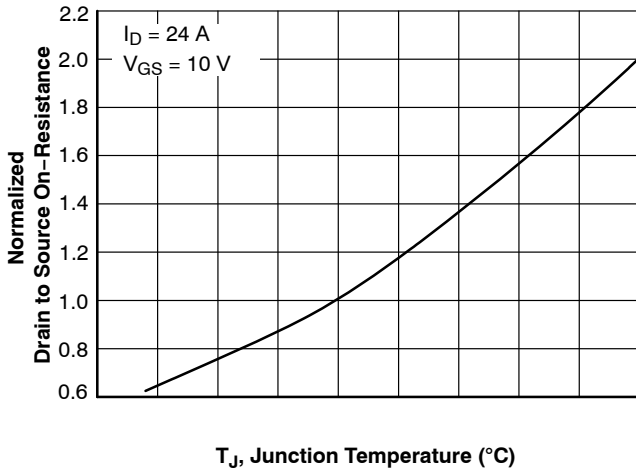


图 3. 标准化导通电阻与结温的关系

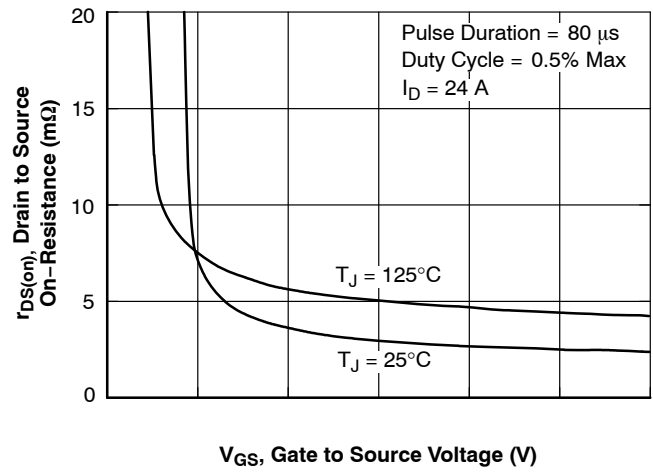


图 4. 导通电阻与栅极-源极电压的关系

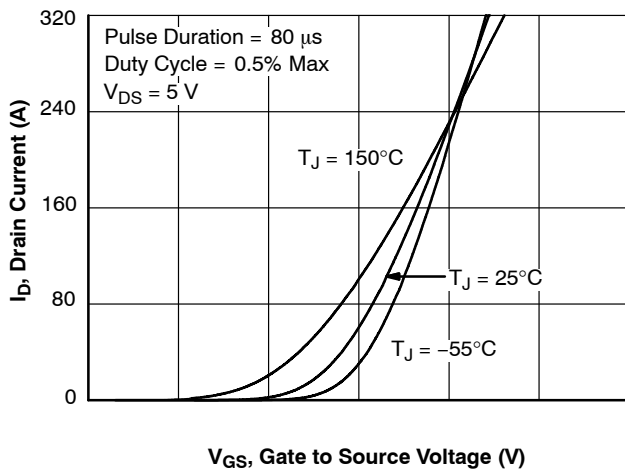


图 5. 传输特性

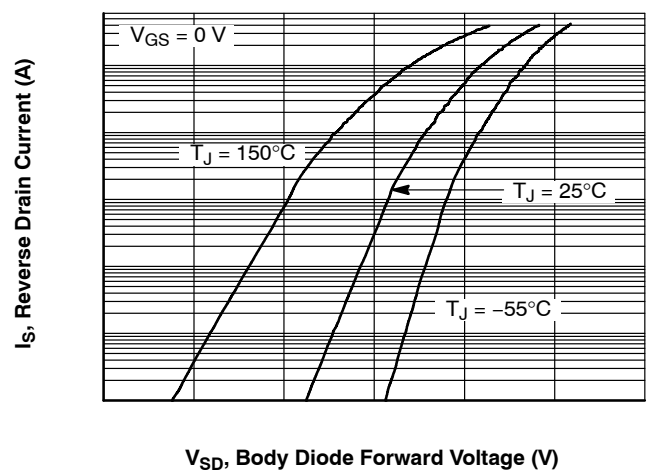


图 6. 源极-漏极二极管正向电压与源极电流的关系

FDMT800100DC

典型特性 ($T_J = 25^\circ\text{C}$, 除非另有说明) (continued)

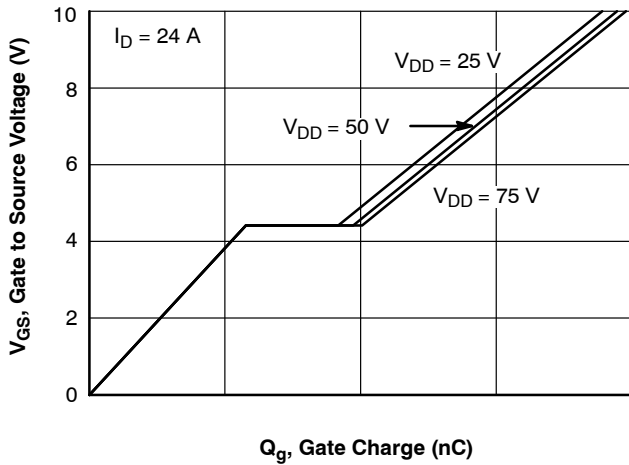


图 7. 栅极电荷特性

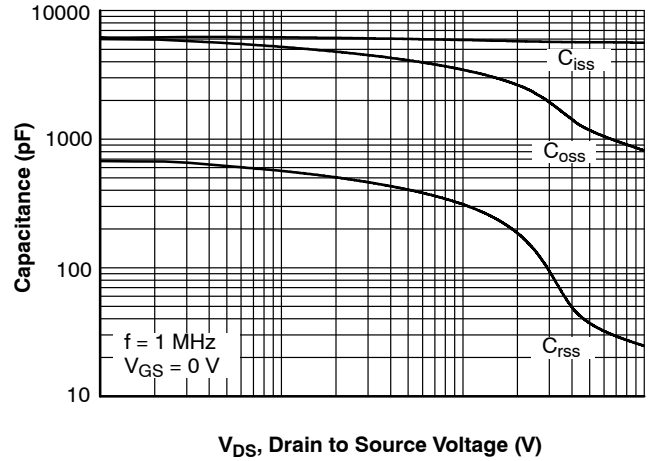


图 8. 电容与漏极-源极电压的关系

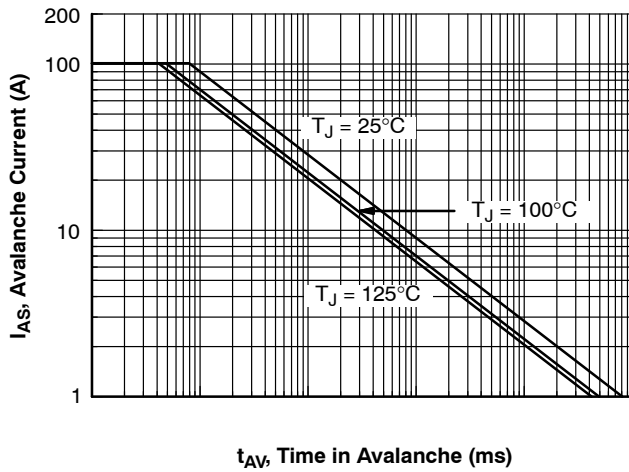


图 9. 非箝位电感开关能力

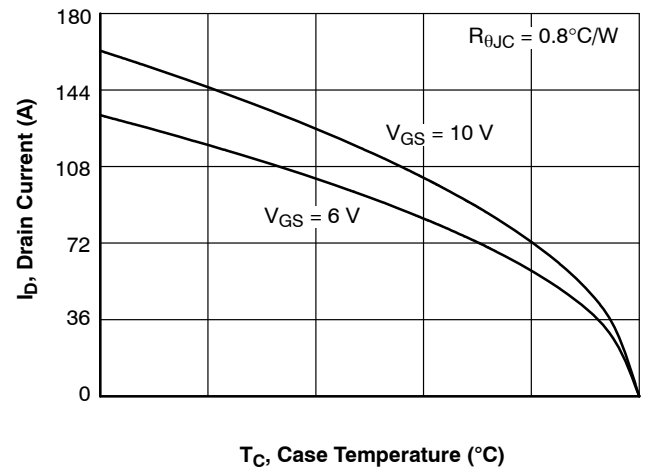


图 10. 最大连续漏极电流与壳温的关系

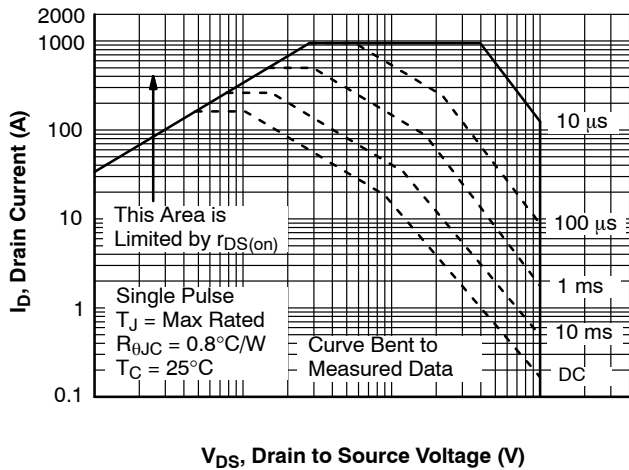


图 11. 正向偏压安全工作区

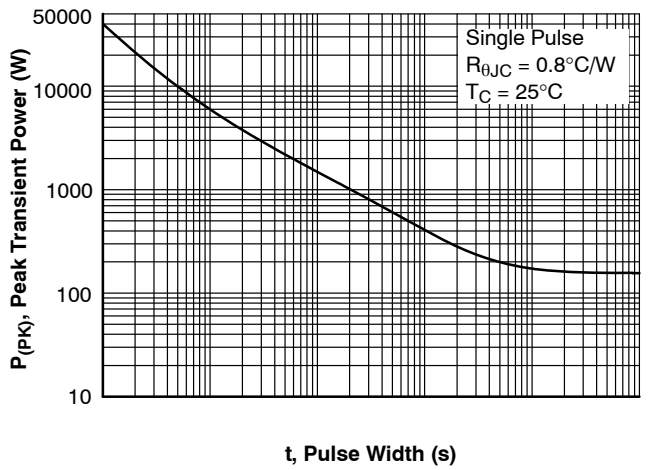


图 12. 单个脉冲最大功耗

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典型特性 (T_J = 25°C, 除非另有说明) (continued)

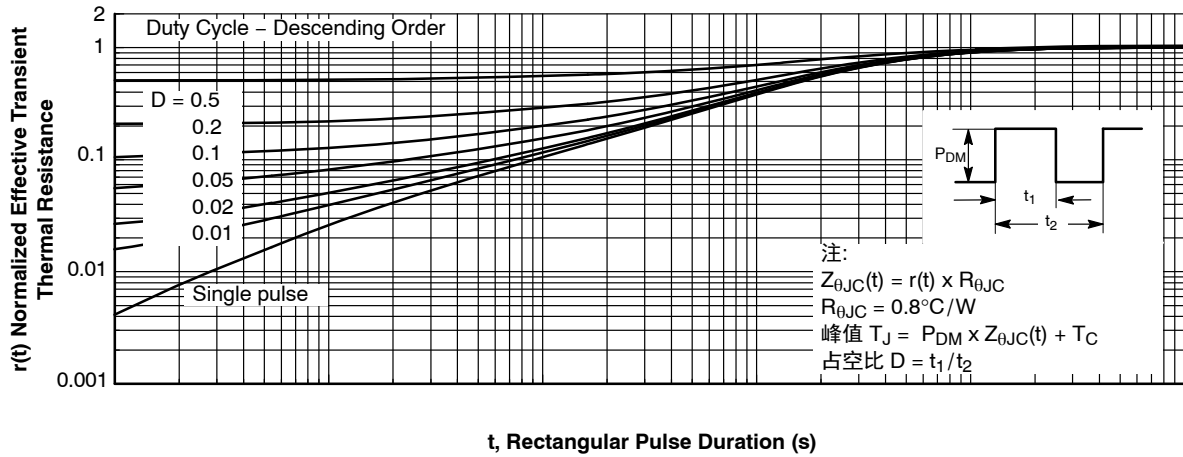


图 13. 结至外壳瞬态热响应曲线

封装标识与订购信息

器件标识	器件	封装形式	卷盘大小	透明封带宽度	Shipping [†]
800100	FDMT800100DC	TDFNW8 8.3 x 8.4, 2P, DUAL COOL, OPTION 2 (Pb-Free and Halide Free)	-	13.3 mm	3000颗/卷

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

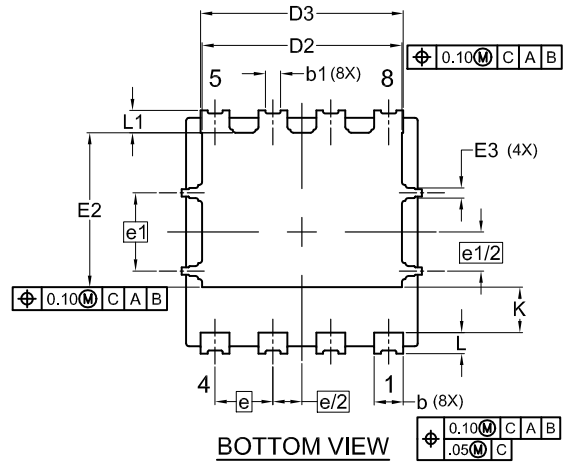
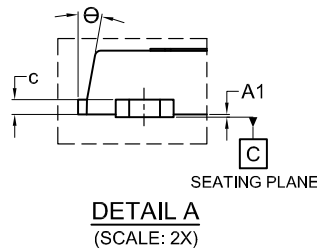
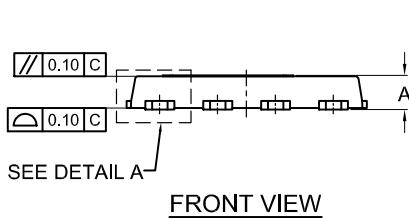
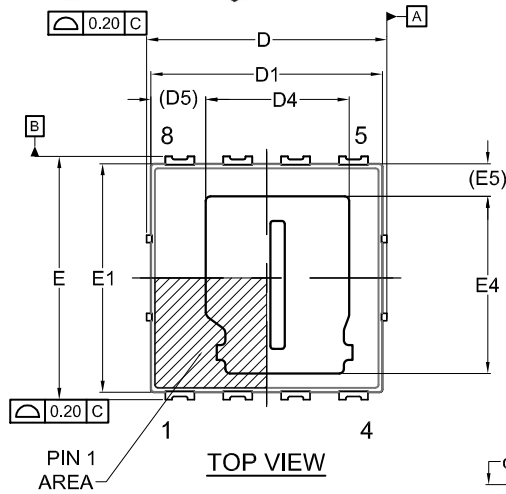
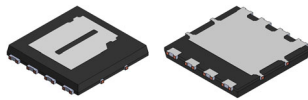
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

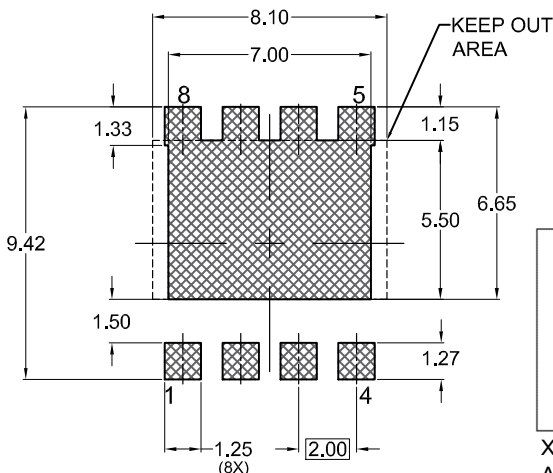


TDFNW8 8.3x8.4, 2P, DUAL COOL, OPTION 2 CASE 507AR ISSUE B

DATE 29 MAR 2021



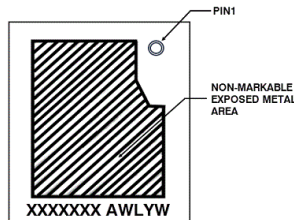
- NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M, 2009.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
 5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



RECOMMENDED LAND PATTERN

(For additional information on our Pb-free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.)

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot Code
Y = Year Code
W = Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.82	0.92	1.02
A1	0.00	--	0.05
b	0.90	1.00	1.10
b1	0.35	0.45	0.55
c	0.23	0.28	0.33
D	8.20	8.30	8.40
D1	7.90	8.00	8.10
D2	6.80	6.90	7.00
D3	6.90	7.00	7.10
D4	4.90	5.05	5.20
D5	1.85 REF		
E	8.30	8.40	8.50
E1	7.80	7.90	8.00
E2	5.24	5.34	5.44
E3	0.25	0.35	0.45
E4	6.08	6.23	6.38
E5	1.13 REF		
e	2.00 BSC		
e/2	1.00 BSC		
e1	2.70 BSC		
e1/2	1.35 BSC		
K	1.50	1.57	1.70
L	0.64	0.74	0.84
L1	0.67	0.77	0.87
θ	0°	--	12°

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DESCRIPTION:	TDFNW8 8.3x8.4, 2P, DUAL COOL, OPTION 2	PAGE 1 OF 1

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